

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.01192	2.09	0.12749
	Doped silicon	Silicon (Si)	7440-21-3	0.55849	97.91	5.97251
Subtotal				0.57041	100	6.1
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.0375	0.1	0.401
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01125	0.03	0.1203
	Copper alloy	Iron (Fe)	7439-89-6	0.0375	0.1	0.401
	Copper alloy	Copper (Cu)	7440-50-8	37.41142	99.77	400.0777
Subtotal				37.49767	100	401
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.84122	4.8	30.384
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	5.91921	10.0	63.3
	Filler	Silica fused	60676-86-0	50.31326	85.0	538.05
	Carbon Black	Carbon black	1333-86-4	0.11838	0.2	1.266
Subtotal				59.19207	100	633
Post-plating	Pure metal	Tin (Sn)	7440-31-5	2.33776	100.0	25
Subtotal				2.33776	100	25
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.16832	100.0	1.8
Subtotal				0.16832	100	1.8
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00468	2.0	0.05
	Lead alloy	Silver (Ag)	7440-22-4	0.00584	2.5	0.0625
	Lead alloy	Lead (Pb)	7439-92-1	0.22326	95.5	2.3875
Subtotal				0.23378	100	2.5
Total				100.00001	100	1069.4

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